PRODUCT CHANGE NOTICE			
PART NUMBER(S):	PCN No.: 06-0130-27b		
Please see attachment.	DATE: June 23, 2006		
PART DESCRIPTION:			
Power Management and Interface Products – Change in Wafer Fabrication Site			
LEVEL OF CHANGE:			
[X] Level I, Customer Approval.	[ ] Level II, Customer Information.		
PRODUCT ATTRIBUTE AFFECTED:			
[ ] Material Change [ ] Design Change [X] Process Change	Data Sheet Change Package Change Packing / Shipping		
[X] Other, Explain: Wafer Fabrication Site Transfer			
DESCRIPTION OF CHANGE:			
Announcing transfer of certain Power Management and Interface Products from Hillview wafer fabrication facility to wafer foundry EPISIL. See attached Product List no. 27b.			
REASON FOR CHANGE:			
Power Management and Interface products as listed are being transferred to external wafer foundry, due to cessation of operations of the Sipex Hillview Wafer Fabrication manufacturing site.			

**FABRICATION PROCESS QUALIFICATION** 

COMPLETED (DATE): August 7, 2006

PRODUCT CHARACTERIZATION COMPLETED AND

SAMPLES\* AVAILABLE (DATE): August 14, 2006

<sup>\*</sup> Samples representative of product from the Product Family being transferred.



PRODUCT CHANGE NOTICE			
EARLIEST DATE OF PRODU SHIPMENTS: February 28, 2	2007		
EFFECTIVITY CHANGE DAT	E OR DATE CODE:	Work week associated wi	th earliest production shipment.
[ ] STANDARD DISTRIBU	TION	[X]	CUSTOM DISTRIBUTION
PERSON TO CONTACT WIT	H QUESTIONS:		
Fred Claussen			
VP Quality Assurance and Re Sipex Corporation Phone Number: 408-935-7644 FAX NUMBER: 408-935-7678	4		



## PRODUCT CHANGE NOTICE

PCN No.: 06-0130-27b

List 27b

SP233ECT

SP233ECT-L

SP233EET

SP233EET-L

SP310ECA

SP310ECA-L

SP310ECP

SP310ECP-L

SP310ECT

SP310ECT-L

SP310EEA

SP310EEA-L

SP310EEP

SP310EEP-L

SP310EET

SP310EET-L

SP312ECA

SP312ECA-L

SP312ECP

SP312ECP-L

SP312ECT

SP312ECT-L

SP312EEA

SP312EEA-L

SP312EEP

SP312EEP-L

SP312EET

SP312EET-L

SP385ECA

SP385ECA-L

SP385ECT

SP385ECT-L

SP385EEA

SP385EEA-L

SP385EET

SP385EET-L